

34. A method as defined in claim 30, wherein the machine is an electron beam direct write system.

5 35. A method as defined in claim 30, wherein the machine is a SCAPEL tool.

36. A method as defined in claim 30, wherein the machine is an extreme ultra-violet imaging tool.

10 37. A method as defined in claim 30, wherein the machine is an ion projection imaging tool.

38. A method as defined in claim 30, wherein the machine is an x-ray imaging system.

15 R-126 39 49. A method as defined in claim 30, wherein the subtracting and calculating after performed on a computer.

R-126 20 40 50. A method as defined in claim 30, wherein the offset values associated with the reference wafer are stored in a calibration file.

R-126 41 51. A method as defined in claim 50, wherein the calibration file is stored on a computer readable medium.